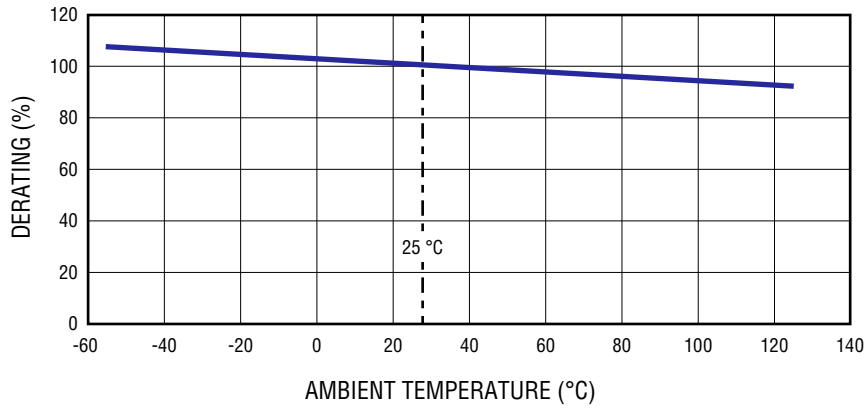
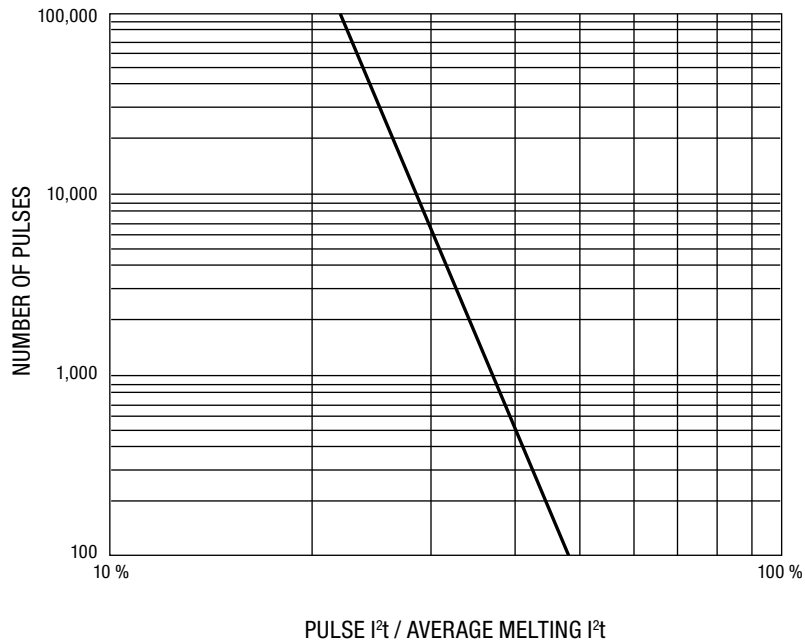


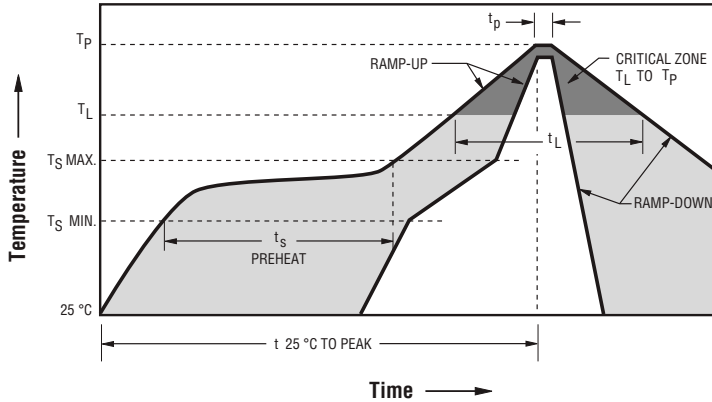
Current Rating Thermal Derating Curve



Pulse Cycle Withstand Capability



Solder Reflow Recommendations

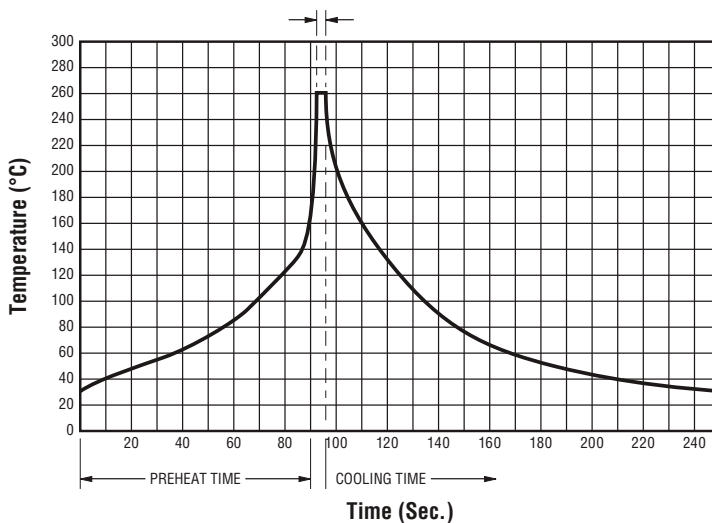


Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. (T_{smin}) Temperature Max. (T_{smax}) Time (t_s) from (T_{smin} to T_{smax})	150 °C 200 °C 60~180 seconds
Ramp Up Rate (T_L to T_p)	3 °C / second max.
Ramp Up Rate (T_{smax} to T_L)	5 °C / second max.
Liquidous Temperature (T_L) Time (t_L) maintained above T_L	217 °C 60~90 seconds
Peak Package Body Temperature (T_p)	235 °C ± 5 °C
Time within 5 °C of actual peak temperature (T_p)	20~30 seconds*
Ramp Down Rate (T_p to T_L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.
Do not exceed	240 °C

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

Solder Wave Recommendations

Peak Temperature (Dwell Time)



Profile Feature	Pb-Free Assembly
Preheat: Temperature Max. (T_{smax}) Time (Min. to Max.)	150 °C 60~90 seconds
Solder Pot Temperature	260 °C max.
Solder Dwell Time	2~3 seconds

Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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